

MBRS410LT3

Preferred Device

Surface Mount Schottky Power Rectifier

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system. Typical applications are AC-DC and DC-DC converters, reverse battery protection, and "ORing" of multiple supply voltages and any other application where performance and size are critical.

Features

- Ultra Low V_F
- 1st in the Market Place with a 10 V_R Schottky Rectifier
- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guard-Ring for Stress Protection
- Pb-Free Package is Available

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- ESD Ratings: Machine Model = C
Human Body Model = 3B

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	10	V
Average Rectified Forward Current (@ $T_L = 110^\circ\text{C}$)	I_O	4.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	150	A
Operating Junction Temperature	T_J	-65 to +125	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

<http://onsemi.com>

**SCHOTTKY BARRIER
RECTIFIERS
4.0 AMPERES, 10 VOLTS**



SMC
CASE 403
PLASTIC

MARKING DIAGRAM



B4L1 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MBRS410LT3	SMC	2500/Tape & Reel
MBRS410LT3G	SMC (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

MBRS410LT3

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min Pad (Note 2)	1 Inch Pad	Unit
Thermal Resistance, Junction-to-Lead	$R_{\theta JL}$	12	7.0	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	109	59	

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 1) ($I_F = 2.0 \text{ A}$) ($I_F = 4.0 \text{ A}$) ($I_F = 8.0 \text{ A}$)	V_F	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	V
		0.31	0.200	
		0.33	0.225	
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $V_R = 5.0 \text{ V}$) (Rated dc Voltage, $V_R = 10 \text{ V}$)	I_R	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	mA
		2.0	100	
		5.0	200	

1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.
2. Mounted with Minimum Recommended Pad Size, PC Board FR4.

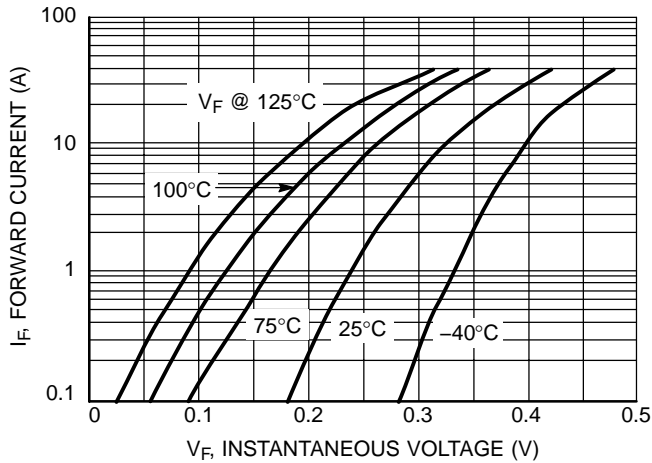


Figure 1. Typical Forward Voltage

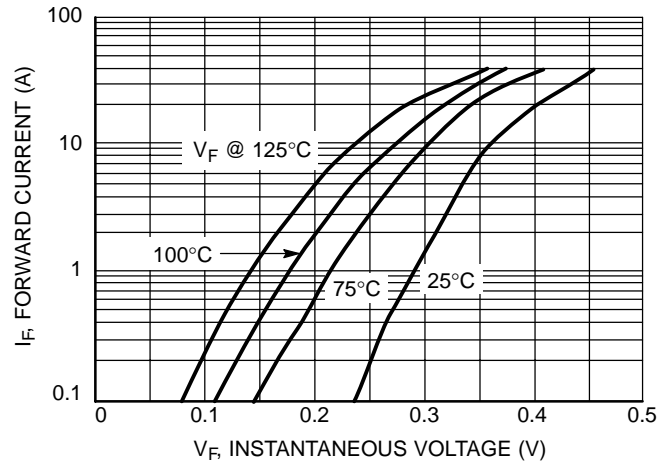


Figure 2. Maximum Forward Voltage

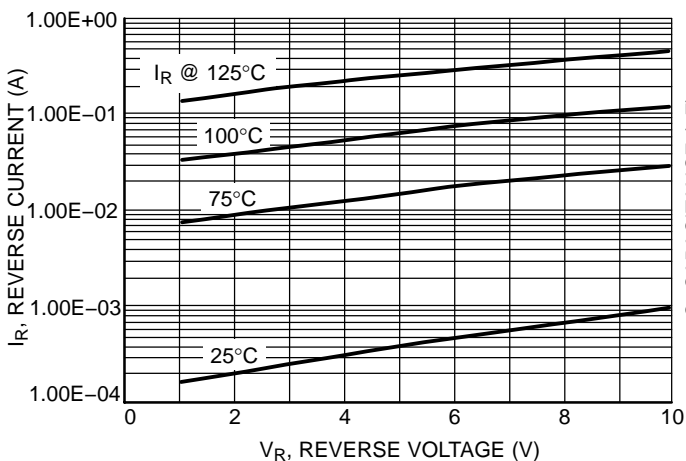


Figure 3. Typical Reverse Current

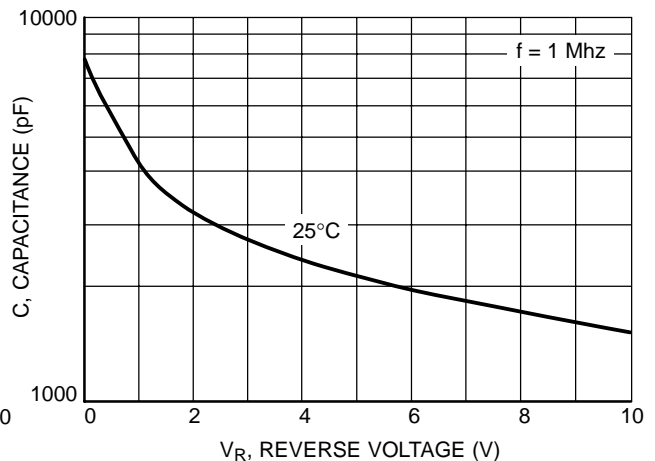


Figure 4. Typical Capacitance

MBRS410LT3

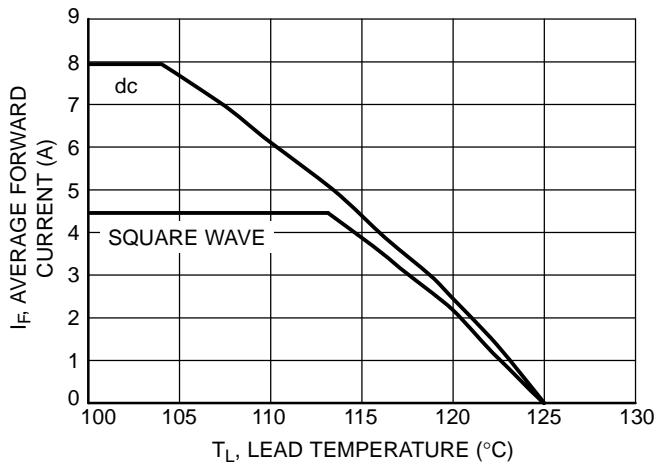


Figure 5. Current Derating (Junction-to-Lead)

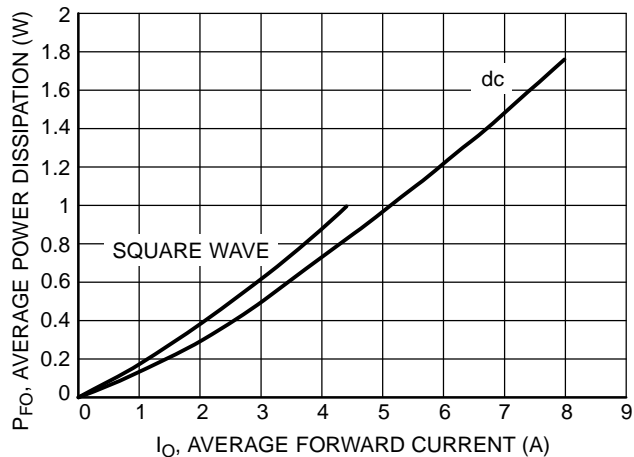


Figure 6. Forward Power Dissipation

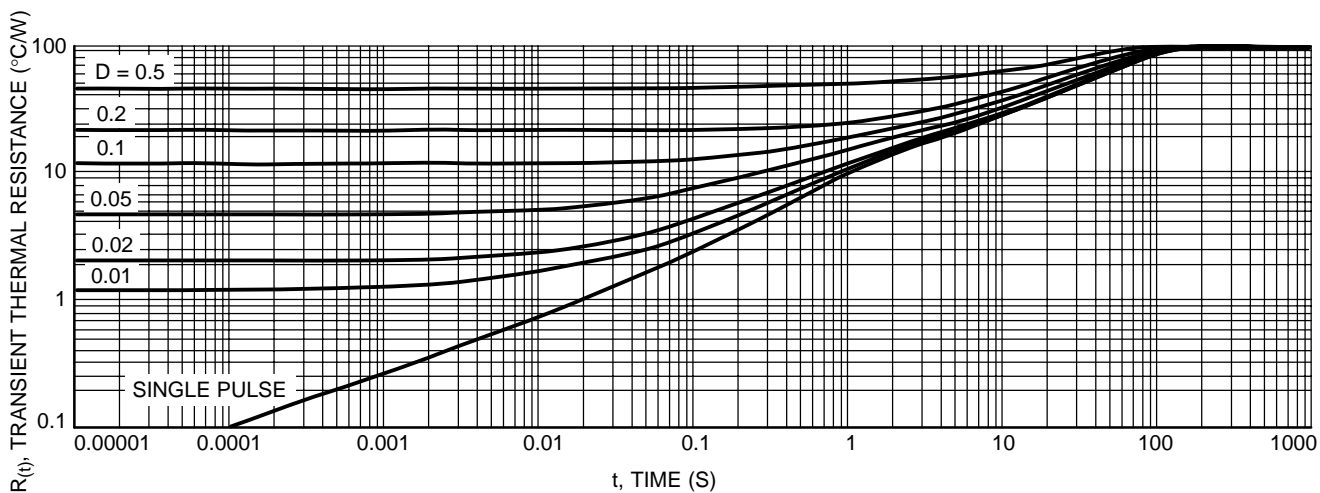


Figure 7. Thermal Response, Junction-to-Ambient (min pad)

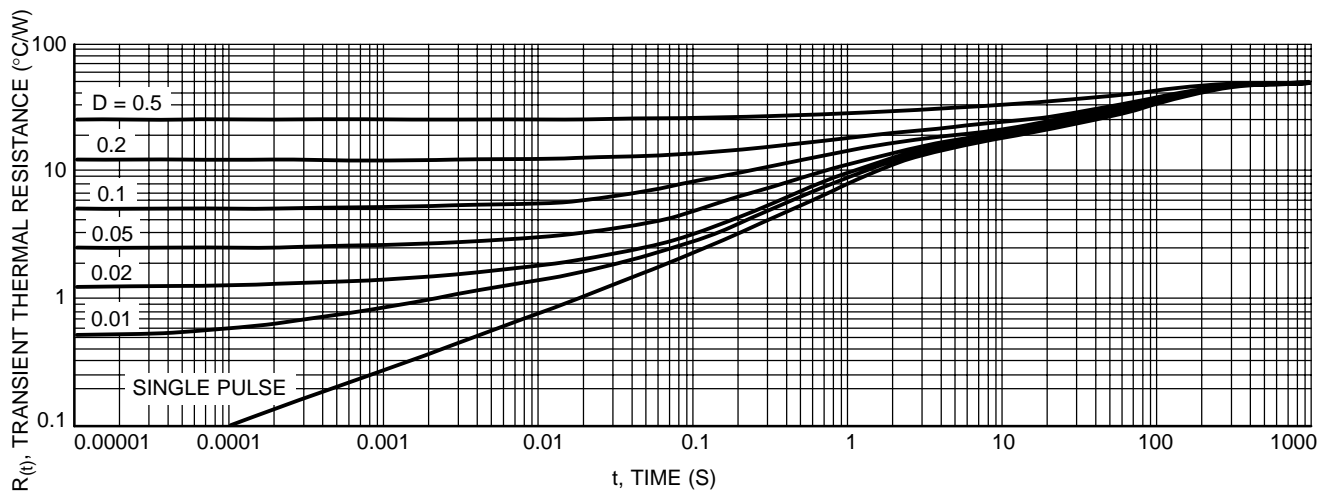
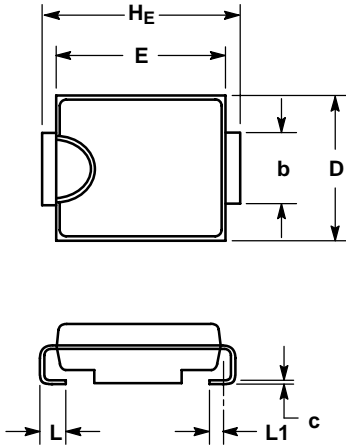


Figure 8. Thermal Response, Junction-to-Ambient (1 inch pad)

MBRS410LT3

PACKAGE DIMENSIONS

SMC
PLASTIC PACKAGE
CASE 403-03
ISSUE E

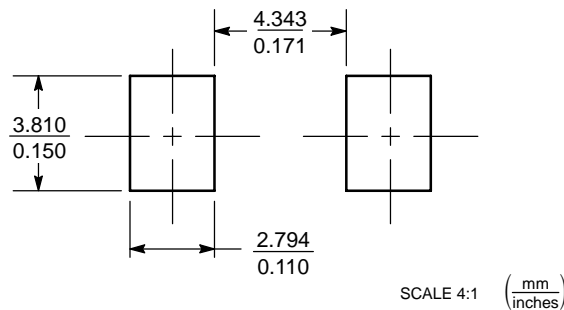


NOTES:


1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.
4. 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.13	2.41	0.075	0.084	0.095
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	2.92	3.00	3.07	0.115	0.118	0.121
c	0.15	0.23	0.30	0.006	0.009	0.012
D	5.59	5.84	6.10	0.220	0.230	0.240
E	6.60	6.86	7.11	0.260	0.270	0.280
HE	7.75	7.94	8.13	0.305	0.313	0.320
L	0.76	1.02	1.27	0.030	0.040	0.050
L1	0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 61312, Phoenix, Arizona 85082-1312 USA
Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada
Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051
Phone: 81-3-5773-3850

ON Semiconductor Website: <http://onsemi.com>

Order Literature: <http://www.onsemi.com/litorder>

For additional information, please contact your local Sales Representative.